

Patent



Customer No. 31561
Application No.: 10/708,488
Docket No. 12476-US-PA

IPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Kao et al
Application No. : 10/708,488
Filed : March 07, 2004
For : METHOD OF FORMING BOND MICROSTRUCTURE
Examiner :
Art Unit : 1725

ASSISTANT COMMISSIONER FOR PATENTS
Arlington, VA22202

Dear Sirs:

Transmitted herewith is a certified copy of Taiwan Application No.: 092135508, filed on: 2003/12/16.

A return prepaid postcard is also included herewith.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Dated: July 15, 2004

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